











**TPS3847** 

## ZHCSCT8A - AUGUST 2014-REVISED MARCH 2015

# TPS3847 18V、380nA 电压监视器

## 特性

- 超低电源电流: 380nA
- 宽电源电压范围: 4.5V 至 18V
- 高阈值精度: ±2.5%
- 内部滞后
- 推挽输出
- 延迟时间 20ms (最大值)
- 厂家调整的固定电压阈值
- 特定工作温度范围: -40°C 至 +85°C
- 工作温度范围: -40°C 至 +105°C
- 封装: 5 引脚 SOT

## 应用

- 便携式和电池供电类设备
- 台式机、笔记本电脑和超级本
- 工业系统
- 服务器
- 安防系统

## 3 说明

TPS3847 系列器件具有宽范围工作电压和超低电流, 可监视电源引脚电压。 每当 VCC 电源电压降至厂家 调整的复位阈值电压以下,器件就会将一个低电平有效 复位信号置为有效。 当 VCC 电压升至阈值电压以上 20ms (最大值) 后,复位输出保持有效。

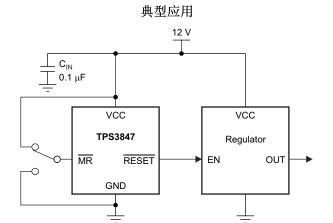
TPS3847 具有 380nA 超低流耗以及 18V 电压, 是低 功耗便携式应用的理想选择。

TPS3847 具有精密的厂家调节阈值电压和极低功耗运 行特性。 TPS3847 采用符合行业标准的 5 引脚 SOT 封装。

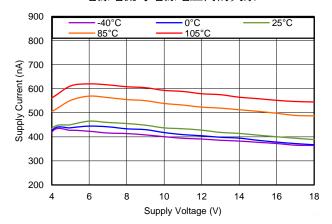
器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸(标称值)
TPS3847	小外形尺寸晶体管 (SOT) (5)	2.90mm x 1.60mm

(1) 要了解所有可用封装,请见数据表末尾的封装选项附录。



## 电源电流与电源电压间的关系





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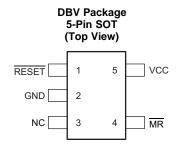
# 4 修订历史记录

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<ul> <li>已更改器件名称以反映整个器件系列</li></ul>	Page
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Added condition to      Z	6
• Changed Y-axis in 图 12	<mark>7</mark>
	10
Changed title of Typical Application section	12



# **5 Pin Configuration and Functions**



## **Pin Functions**

PIN			
NAME NO. I/O			DESCRIPTION
GND	2	_	Ground
MR	4	I	Manual reset. Pull this pin to a logic low to force the $\overline{RESET}$ output low regardless of the voltage on VCC. After the $\overline{MR}$ pin is pulled to a logic high, the $\overline{RESET}$ output goes high after the $\overline{RESET}$ delay time $(t_d)$ if the voltage on VCC is higher than the positive-going threshold voltage.
NC	3	_	No internal connection.
RESET	1	0	Active low reset output. $\overline{\text{RESET}}$ stays low as long as the voltage on VCC is below the factory trimmed threshold voltage. $\overline{\text{RESET}}$ transitions from low to high once the VCC voltage is above the positive-going threshold voltage for a specified time (t <sub>d</sub> ). $\overline{\text{RESET}}$ is a push-pull output.
VCC	5	I	Power supply and monitored voltage. TI recommends adding a small 0.1-µF bypass capacitor near the VCC pin.



## 6 Specifications

## 6.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating junction temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Voltage	VCC	-0.3	+20	٧
	MR	-0.3	VCC + 0.3	٧
	RESET	-0.3	+5.5	٧
Current	RESET		10	mA
Temperature <sup>(2)</sup>	Operating junction, T <sub>J</sub>	-40	+105	°C
remperature	Storage, T <sub>stg</sub>	-65	+150	°C

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods my affect device reliability.

## 6.2 ESD Ratings

			VALUE	UNIT
\/	Flootroototic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±4000	V
V <sub>(ESD)</sub> E	Electrostatic discharge	lectrostatic discharge  Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)		V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

## 6.3 Recommended Operating Conditions

over operating junction temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V <sub>(VCC)</sub>	Power supply voltage	4.5		18	V
$V_{(\overline{MR})}$	MR pin voltage	0	1.2	VCC	٧
$V_{(\overline{RESET})}$	RESET pin voltage	0		5	٧
I <sub>(RESET)</sub>	RESET pin current	0		2	mA
C <sub>IN</sub>	Input capacitor	0	0.1		μF
TJ	Junction temperature	-40	+25	+85	ů

#### 6.4 Thermal Information

		TPS3847	
	THERMAL METRIC <sup>(1)</sup>	DBV (SOT)	UNIT
		5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	208.5	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	123.3	
$R_{\theta JB}$	Junction-to-board thermal resistance	37.2	°C/W
ΨЈТ	Junction-to-top characterization parameter	14.6	C/VV
$\Psi_{JB}$	Junction-to-board characterization parameter	36.3	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.

<sup>(2)</sup> As a result of the low dissipated power in this device, it is assumed that the junction temperature is equal to the ambient temperature.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



## 6.5 Electrical Characteristics

At  $T_J = -40^{\circ}\text{C}$  to +85°C, 4.5 V <  $V_{CC}$  < 18 V, and  $C_{IN} = 0.1~\mu\text{F}$  (unless otherwise noted). Typical values are at  $T_J = 25^{\circ}\text{C}$ .

	PARAMETER		ST CONDITIONS	MIN	TYP	MAX	UNIT
POWER	RSUPPLY					l.	
V <sub>(VCC)</sub>	Input supply voltage range			4.5		18	V
V <sub>VO</sub>	Minimum V <sub>(VCC)</sub> voltage for valid output <sup>(1)</sup>	$I_{OL} = 1 \mu A, V_{Ol}$	_ = 400 mV			0.8	V
			$T_J = 25^{\circ}C, V_{(VCC)} = 18 V$		380		nA
$I_{(VCC)}$	Supply current (into VCC pin)	Output not connected	$T_J = 25^{\circ}C$			750	nA
		00111100100	$-40$ °C $\leq T_J \leq +85$ °C			900	nA
MONIT	ORED THRESHOLD		, and the second se			·	
	Negative going input threshold	$T_J = 25^{\circ}C$			±0.5%		
.,	accuracy			-2.5%		+2.5%	
V <sub>IT</sub>	No matical main at the scale and coult are	TPS3847085		8.2875	8.5	8.7125	V
	Negative-going threshold voltage	TPS3847108		10.53	10.8	11.07	V
.,	Livetanasia valtana	TPS3847085		0.	11 × V <sub>IT</sub>		V
$V_{HYS}$	Hysteresis voltage	TPS3847108		0.0	35 × V <sub>IT</sub> _		V
OUTPU	т						
		0.9 V < V <sub>(VCC)</sub>	< 2.4 V, I <sub>OL</sub> = 10 μA		0.009	0.4	V
$V_{OL}$	Push-pull low-level output voltage (RESET)	2.4 V ≤ V <sub>(VCC)</sub>	< 4.5 V, I <sub>OL</sub> = 250 μA		0.015	0.4	V
	(RESET)	4.5 V ≤ V <sub>(VCC)</sub>	≤ 18 V, I <sub>OL</sub> = 2 mA		0.09	0.4	V
				1.6		3.1	V
	Push-pull high-level output voltage	$I_{OH} = -2 \text{ mA}$	V <sub>(VCC)</sub> = 18 V		2.45		V
$V_{OH}$	(RESET)			3		4	V
		$I_{OH} = -10 \mu A$	V <sub>(VCC)</sub> = 18 V		3.55		V
MR PIN		+	1 1 1				
V <sub>IL</sub>	Low-level input voltage					0.4	V
V <sub>IH</sub>	High-level input voltage			1.2			V
I <sub>lkg(MR)</sub>	MR leakage current	MR High, V <sub>(VC)</sub>	<sub>C)</sub> = 18 V		-23		nA

<sup>(1)</sup> The lowest supply voltage  $(V_{(VCC)})$  at which  $\overline{RESET}$  is valid.  $t_{RISE(VCC)} \ge 15 \,\mu s/V$ , where  $t_{RISE}$  is the rise time.

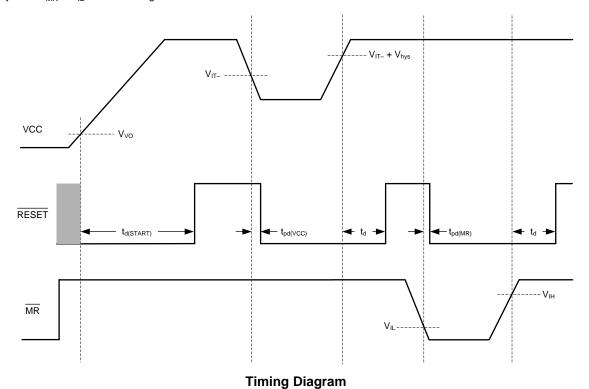


## 6.6 Timing Requirements

At  $T_J = -40$ °C to +85°C, 4.5 V < VCC < 18 V, and  $C_{IN} = 0.1~\mu F$  (unless otherwise noted). Typical values are at  $T_J = 25$ °C.

	PARAMETER	MIN	TYP	MAX	UNIT
t <sub>d</sub>	RESET delay time (1)		4.5	20	ms
t <sub>d(START)</sub>	Startup delay time (2)		6.5	40	ms
t <sub>pd(VCC)</sub>	Propagation delay for VCC falling <sup>(3)</sup>		55		μs
t <sub>pd(MR)</sub>	Propagation delay MR falling (4)		50		μs
t <sub>P(MR)</sub>	MR minimum high to low pulse duration for RESET low		50		μs

- Delay from when  $V_{(VCC)} \ge V_{IT-}$  or  $V_{MR} \ge V_{IH}$  until  $\overline{RESET}$  goes high when  $V_{(VCC)}$  starts from above the specified minimum  $V_{(VCC)}$ . Measured with 5% overdrive. (1)
- (2) When V<sub>(VCC)</sub> starts from less than the specified minimum V<sub>(VCC)</sub> and then exceeds V<sub>th</sub>, RESET goes high after the startup delay (t<sub>d(START)</sub>) instead of the RESET delay time (t<sub>d</sub>). Measured with 5% overdrive.
   (3) Delay from V<sub>(VCC)</sub> < V<sub>th</sub> until RESET goes low. Measured with 8% overdrive.
   (4) Delay from V<sub>MR</sub> < V<sub>IL</sub> until RESET goes low. Measured with 8% overdrive.

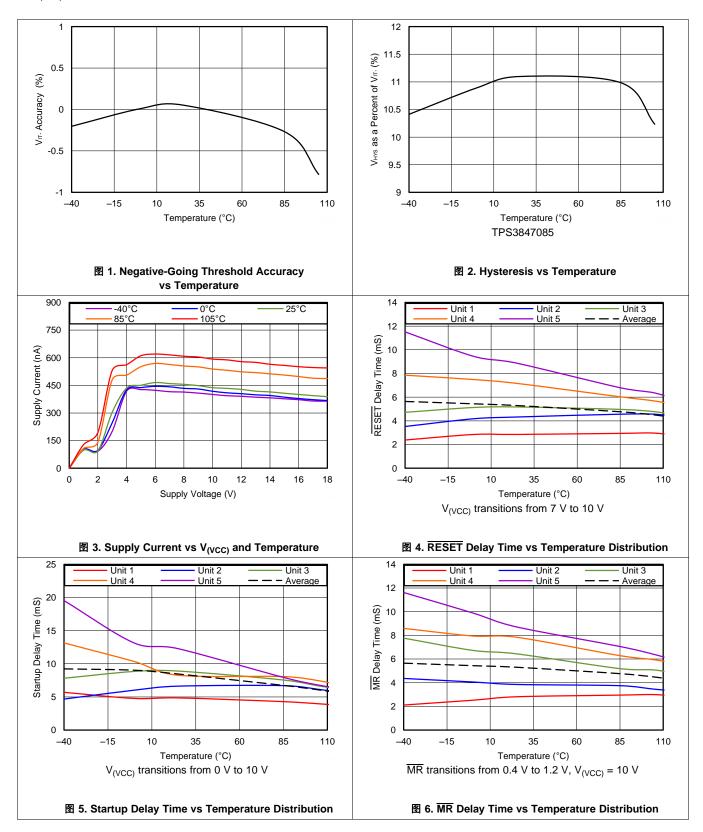


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## 6.7 Typical Characteristics

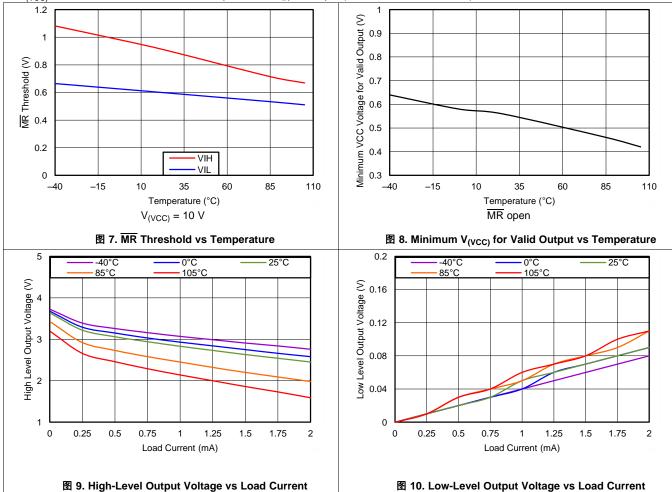
At  $V_{(VCC)} = 18$  V,  $\overline{MR} = 1.2$  V,  $\overline{RESET} = open$ , and  $C_{IN} = 0.1$   $\mu F$  (unless otherwise noted).



# TEXAS INSTRUMENTS

## Typical Characteristics (接下页)

At  $V_{(VCC)}$  = 18 V,  $\overline{MR}$  = 1.2 V,  $\overline{RESET}$  = open, and  $C_{IN}$  = 0.1  $\mu F$  (unless otherwise noted).





## 7 Detailed Description

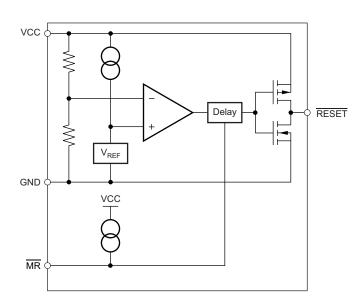
#### 7.1 Overview

The TPS3847 is a family of ultralow-current supervisors for high-voltage applications that are specified from –40°C to +85°C and operational up to 105°C (see the *Typical Characteristics* section for typical –40°C to +105°C performance).

The  $\overline{\text{RESET}}$  output goes low after the power-supply voltage  $(V_{(VCC)})$  drops below the negative-going input threshold voltage  $(V_{IT-})$ , and after the VCC falling propagation delay  $(t_{pd(VCC)})$  elapses. When  $V_{(VCC)}$  rises above the positive-going reset threshold  $(V_{IT+})$ , which is the negative-going threshold voltage plus the hysteresis  $(V_{IT-} + V_{hys})$ , RESET outputs a high signal after the reset delay time  $(t_d)$  elapses.

The TPS3847 also features a manual reset pin  $(\overline{MR})$  that allows a processor, or other logic devices, to initiate a reset, even when  $V_{(VCC)}$  exceeds  $V_{IT-}$ . A logic low on MR causes RESET to transition to logic low after the MR propagation delay  $(t_{pd(MR)})$  elapses. When MR returns to a logic high and  $V_{(VCC)}$  exceeds  $V_{IT+}$ , RESET transitions to logic high after  $t_d$  elapses.

## 7.2 Functional Block Diagram



## 7.3 Feature Description

#### 7.3.1 Ultralow Supply Current

The TPS3847 uses a unique sampling scheme to maintain an extremely-low average quiescent current of 380 nA. This low quiescent current is ideal for applications that require extremely-low power consumption.

#### 7.3.2 Wide Supply Range

This device has an operational input supply range of 4.5 V to 18 V, allowing for a wide range of applications. This wide supply range is ideal for applications that have either large transients or high dc voltage supplies.

#### 7.3.3 High-Accuracy Negative Threshold

The TPS3847 has a negative threshold accuracy of ±2.5% and uses well-controlled and matched internal resistors to set the threshold voltage in order to eliminate the inaccuracies because of the external resistors. Unlike The TPS3847, voltage supervisors that require external resistors to set the threshold voltage always add inaccuracy to the specified performance.

## Feature Description (接下页)

#### 7.3.4 Push-Pull Output

The TPS3847 has a push-pull output stage that covers many of the common digital logic levels. Push-pull outputs simplify many designs compared to open-drain output devices because push-pull outputs do not require a pull-up resistor or an additional low-voltage rail. Compared to open-drain output devices, push-pull devices reduce power consumption when the output is low because open-drain devices sink current through the pull-up resistor to ground in order to create the logic-low signal.

## 7.3.5 Manual Reset (MR) Input

The manual reset ( $\overline{\text{MR}}$ ) input allows a processor, or other logic devices, to initiate a reset even when the voltage on VCC is greater than  $V_{\text{IT-}}$ . A logic low on  $\overline{\text{MR}}$  causes  $\overline{\text{RESET}}$  to output a logic low. After  $\overline{\text{MR}}$  returns to a logic high and the power-supply voltage is greater than  $V_{\text{IT+}}$ ,  $\overline{\text{RESET}}$  transitions to logic high after the reset delay time ( $t_d$ ) elapses.

#### 7.3.6 VCC Transient Rejection

The TPS3847 has built-in rejection of fast transients on the VCC pin. Transient rejection depends on both the duration and overdrive, or amplitude, of the transient. Overdrive of the transient is measured from the bottom of the transient to the negative threshold voltage  $(V_{IT})$  of the device, as shown in  $\boxed{8}$  11.

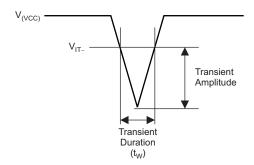


图 11. Voltage Transient Measurement

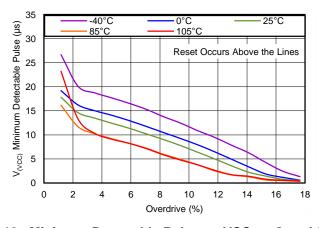


图 12. Minimum Detectable Pulse on VCC vs Overdrive



## Feature Description (接下页)

#### 7.3.7 Controlled Startup Current

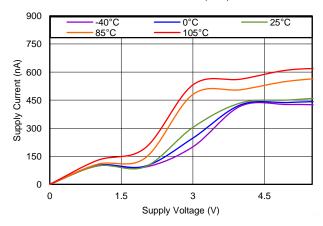


图 13. Supply Current During Startup

## 7.3.8 Low Minimum Supply Voltage for Valid Output

The TPS3847 is designed to have a valid RESET signal, even with a low input supply voltage. 

14 shows that even at −40°C, the TPS3847 typically has a valid output with only 0.65 V on the input supply; at 105°C, that input supply voltage goes down to less than 0.45 V.

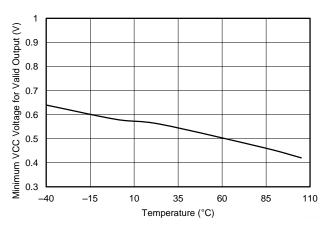


图 14. Minimum Supply Voltage for Valid Output vs Temperature

## 7.4 Device Functional Modes

The TPS3847 has two functional modes:

- 1.  $\overline{MR}$  high: in this mode,  $\overline{RESET}$  is high or low depending on the value of  $V_{(VCC)}$  relative to  $V_{IT-}$ .
- 2.  $\overline{MR}$  low: in this mode,  $\overline{RESET}$  is held low regardless of the value of  $V_{(VCC)}$ .



## 8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 8.1 Application Information

The TPS3847 family consists of wide-operating voltage, ultralow-current devices that monitor the power-supply voltage. The device asserts an active-low reset signal whenever the supply voltage drops below the factory-trimmed reset. The ultralow current consumption of 380 nA combined with 18-V capability makes the TPS3847 ideal for use in low-power and portable applications.

## 8.2 Typical Application

Wide operating voltage and threshold options make the TPS3847 well suited for monitoring dual- and triple-cell, lithium-ion battery applications. ₹ 15 shows the TPS3847 used to disable a buck converter when the cell voltage discharges below the threshold voltage. When the cell voltage reaches V<sub>IT−</sub>, the enable pin of the TPS62120 is driven low, placing the buck converter in a low-current, shutdown state.

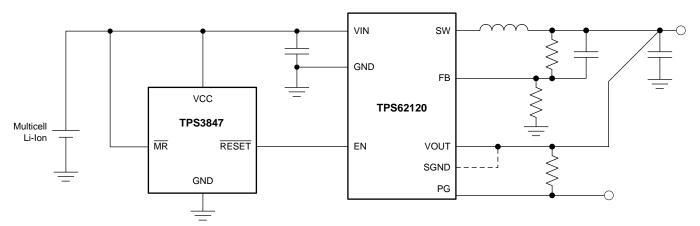


图 15. Disabled Buck Converter

#### 8.2.1 Design Requirements

## 8.2.1.1 Input Capacitor

The TPS3847 uses a unique sampling scheme to maintain an extremely low average quiescent current of 380 nA. However, this current rises to approximately 12 µA for approximately 500 µs while the TPS3847 refreshes the reference voltage. This refresh pulse typically occurs every 200 ms. If the source impedance to the supply voltage is high, then the additional current during sampling may trigger a false reset as a result of the voltage drop from the supply to the VCC pin. For sources with a high impedance, or applications with long or thin VCC traces, add a 0.1-µF or larger bypass capacitor near the VCC pin. Adding this bypass capacitor effectively keeps the average current supplied from the input source close to 380 nA, reducing the voltage droop caused by the refresh pulse, and is good analog design practice.



## Typical Application (接下页)

#### 8.2.1.2 Driving Bidirectional Reset Pins

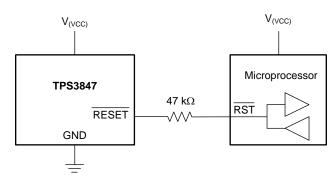


图 16. Connection to Bidirectional Reset Pin

## 8.2.1.3 Manual Reset (MR) Input

The manual reset ( $\overline{MR}$ ) input allows a processor, or other logic devices, to initiate a reset. A logic low on  $\overline{MR}$  causes  $\overline{RESET}$  to transition to logic low. After  $\overline{MR}$  returns to a logic high and  $V_{(VCC)}$  is greater than  $V_{IT+}$ ,  $\overline{RESET}$  transitions to a logic high after the reset delay time,  $t_d$ , elapses.

Note that internal to the <u>device MR</u> is connected to a very <u>small</u> current source that goes from the internal subregulated voltage to the <u>MR</u> node. If the logic signal driving <u>MR</u> does not exceed 3 V, there is 25 nA of additional current drawn from the <u>input</u> supply because of this current source. Do not leave this pin floating; either drive this pin above or below the <u>MR</u> high and low input levels. Tie <u>MR</u> directly to VCC if not used.

#### 8.2.1.4 Threshold Overdrive

Threshold overdrive is how much  $V_{(VCC)}$  exceeds the specified threshold, and is important to know because the smaller the overdrive, the slower the RESET response. Threshold overdrive is calculated as a percent of the threshold in question, as shown in  $\Delta \vec{x}$  1:

Overdrive = 
$$|(V_{(VCC)} / V_{IT} - 1) \times 100\%|$$

where:

V<sub>IT</sub> is either V<sub>IT</sub> or V<sub>IT</sub>, depending on whether calculating the overdrive for the negative-going threshold or the positive-going threshold, respectively.

For positive-going events, after the overdrive is greater than 5%, the changes to  $t_d$  are negligible because of the significantly longer delay time. When overdrive is less than 5%,  $t_d$  can increase to 200 ms while the device waits for the next voltage reference refresh pulse.

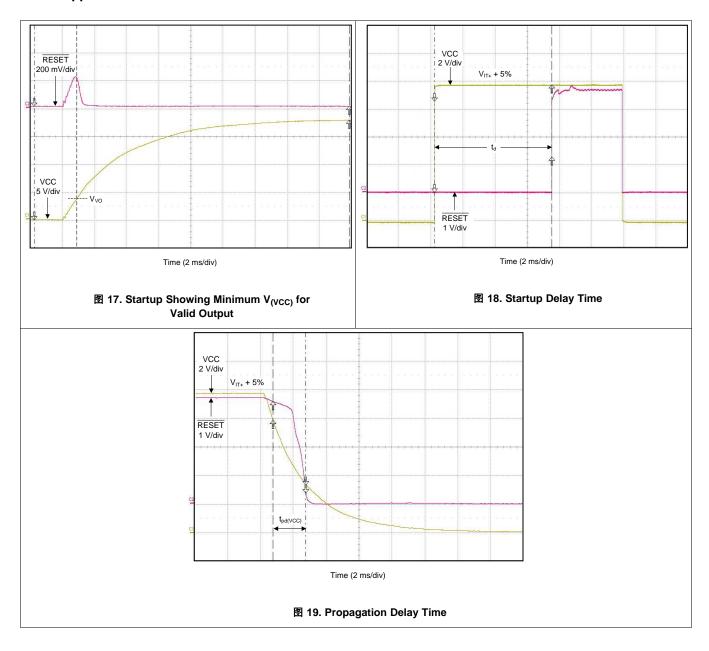


## Typical Application (接下页)

#### 8.2.2 Detailed Design Procedure

- Select desired device based on the threshold voltage.
- Ensure that the trace from the input supply to the VCC pin is low impedance in order to avoid false reset signals during the refresh cycle. If the impedance is too high, add an input capacitor of 0.1-µF or larger close to the VCC pin (see the *Input Capacitor* section).
- If the RESET of the TPS3847 is driving a bidirectional pin, place a resistor between the output of the TPS3847 and the bidirectional pin (see the *Driving Bidirectional Reset Pins* section).

## 8.2.3 Application Curves





#### 8.3 Do's and Don'ts

Connect a 0.1-µF to 1.0-µF low equivalent series resistance (ESR) capacitor between the VCC pin and the GND pin.

Connect the  $\overline{MR}$  pin to a voltage higher than 1.2 V in order for  $\overline{RESET}$  to go high or low, depending on the value of  $V_{(VCC)}$  relative to  $V_{IT-}$ .

Connect the  $\overline{MR}$  pin to a voltage lower than 0.4 V in order to hold  $\overline{RESET}$  low, regardless of the value of  $V_{(VCC)}$ . Connect the  $\overline{MR}$  pin to the VCC pin if  $\overline{MR}$  functionality is not used.

Do not connect the VCC pin to a high-impedance supply without a  $0.1-\mu F$  to  $1.0-\mu F$  low equivalent series resistance (ESR) bypass capacitor.

Do not use a thin, long trace to connect the VCC pin to the input supply without a  $0.1-\mu F$  to  $1.0-\mu F$  low ESR bypass capacitor.

Do not leave the MR pin floating.

## 9 Power Supply Recommendations

These devices are designed to operate from an input supply with a voltage range between 4.5 V and 18 V. Use a low-impedance power supply to eliminate inaccuracies caused by the current during the voltage-reference refresh.

## 10 Layout

## 10.1 Layout Guidelines

Make sure the connection to the VCC pin is low impedance and able to carry 12 μA without a significant voltage drop. Place a 0.1-μF bypass capacitor near the VCC pin if the 12-μA current causes too much voltage droop.

#### 10.2 Layout Example

The layout example in  $\boxtimes$  20 shows how the TPS3847 is laid out on a printed circuit board (PCB). Although not required, use  $C_{IN}$  for best device performance.

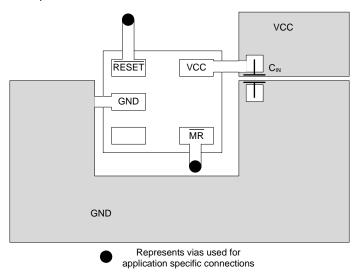


图 20. Layout Example



## 11 器件和文档支持

#### 11.1 器件支持

#### 11.1.1 器件命名规则

TPS3847xxxyyy 是此器件的通用命名惯例。 TPS3847 代表此类器件所属系列,xxx 用于显示负向阈值电压(第二 个数字之后的小数点省略), yyy 保留用于封装标识符。

示例: TPS3847085DBV

系列: TPS3847 负向阈值电压: 8.5V DBV 封装: 5 引脚 SOT

## 11.2 文档支持

#### 11.2.1 相关文档

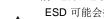
《TPS3847085EVM-577 评估模块用户指南》, SBVU023

《TPS62120 数据表》, SLVSAD5

## 11.3 商标

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#### 11.4 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序,可 能会损坏集成电路。



▲ SSD 的损坏小至导致微小的性能降级,大至整个器件故障。 精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可 能会导致器件与其发布的规格不相符。

#### 11.5 术语表

SLYZ022 — TI 术语表。

这份术语表列出并解释术语、首字母缩略词和定义。

## 12 机械封装和可订购信息

以下页中包括机械封装和可订购信息。 这些信息是针对指定器件可提供的最新数据。 这些数据会在无通知且不对 本文档进行修订的情况下发生改变。 欲获得该数据表的浏览器版本,请查阅左侧的导航栏。



## PACKAGE OPTION ADDENDUM



10-Dec-2020

#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TPS3847085DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	PC7I	Samples
TPS3847085DBVT	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	PC7I	Samples
TPS3847108DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	ZBYD	Samples
TPS3847108DBVT	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 105	ZBYD	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

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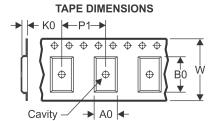
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## PACKAGE MATERIALS INFORMATION

www.ti.com 24-Apr-2020

## TAPE AND REEL INFORMATION





_	_	
		3
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3847085DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3847085DBVT	SOT-23	DBV	5	250	178.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TPS3847108DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
TPS3847108DBVT	SOT-23	DBV	5	250	178.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3

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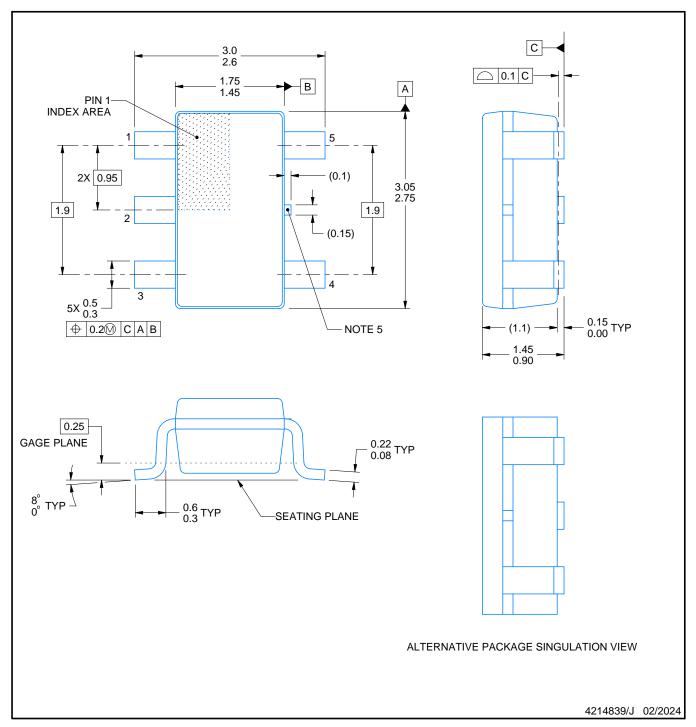


\*All dimensions are nominal

7 ill difficiente die Herrinia											
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)				
TPS3847085DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0				
TPS3847085DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0				
TPS3847108DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0				
TPS3847108DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0				



SMALL OUTLINE TRANSISTOR



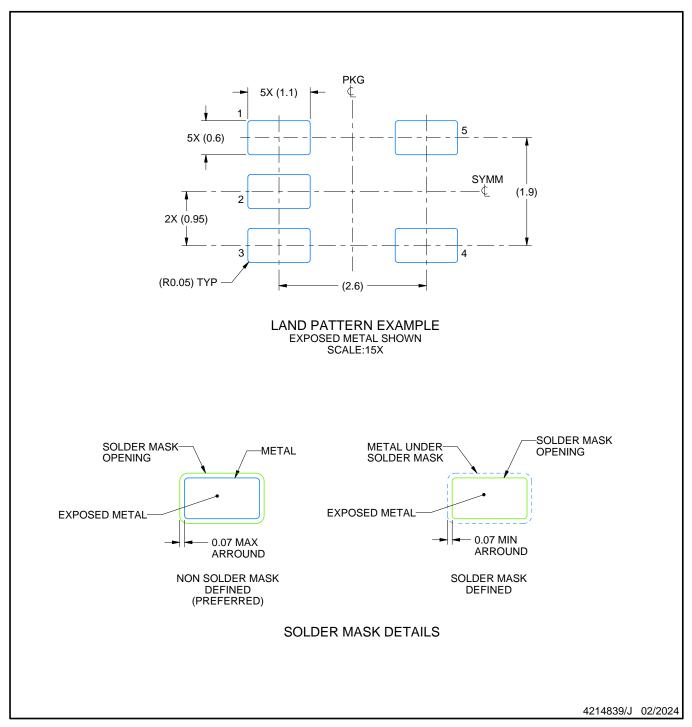
#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
  3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



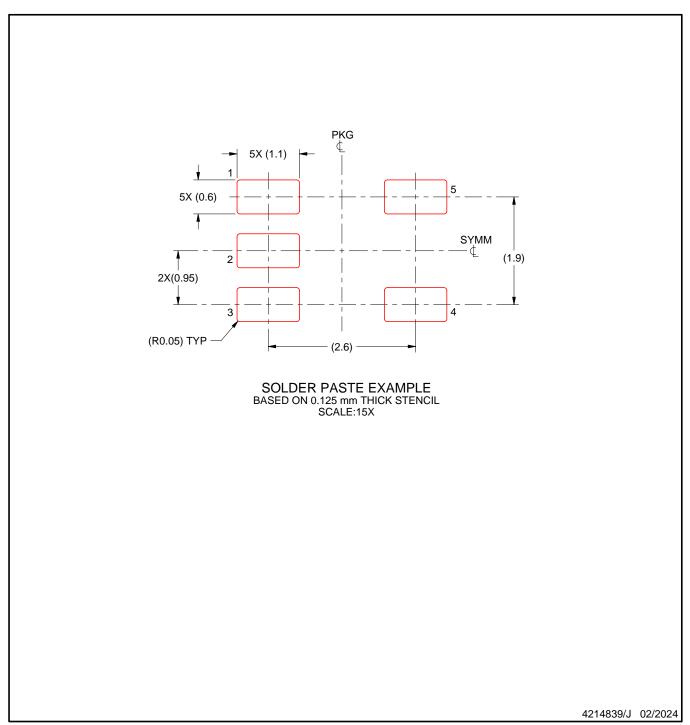
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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